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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Not For New Designs
Core Processor	CPU32
Core Size	32-Bit Single-Core
Speed	16MHz
Connectivity	EBI/EMI, SCI, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	15
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	132-BQFP Bumpered
Supplier Device Package	132-PQFP (24.13x24.13)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc68332gmeh16

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1.4 Address Map

The following figure is a map of the MCU internal addresses. The RAM array is positioned by the base address registers in the associated RAM control block. Unimplemented blocks are mapped externally.

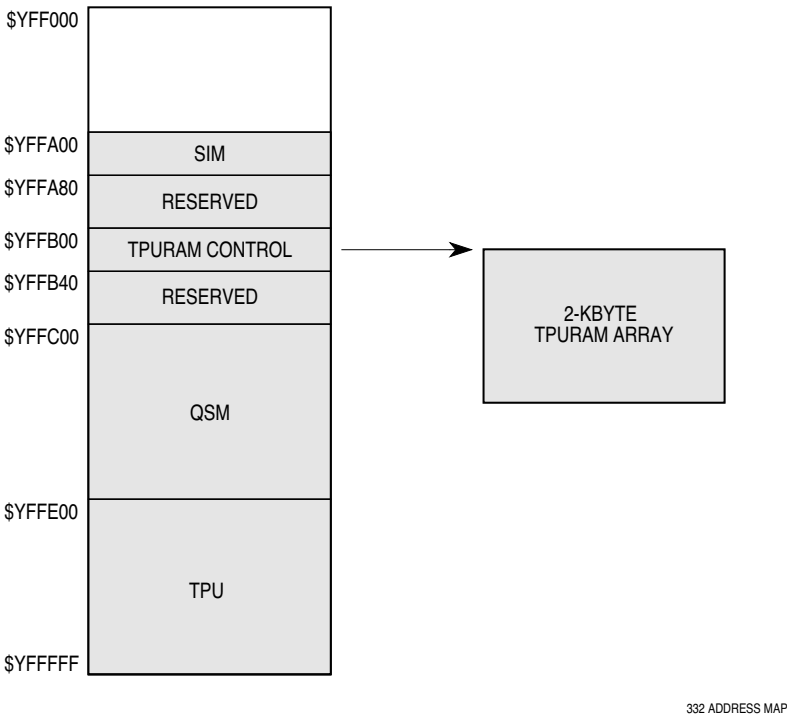


Figure 4 MCU Address Map

1.5 Intermodule Bus

The intermodule bus (IMB) is a standardized bus developed to facilitate both design and operation of modular microcontrollers. It contains circuitry to support exception processing, address space partitioning, multiple interrupt levels, and vectored interrupts. The standardized modules in the MCU communicate with one another and with external components through the IMB. The IMB in the MCU uses 24 address and 16 data lines.

2 Signal Descriptions

2.1 Pin Characteristics

The following table shows MCU pins and their characteristics. All inputs detect CMOS logic levels. All inputs can be put in a high-impedance state, but the method of doing this differs depending upon pin function. Refer to the table, MCU Driver Types, for a description of output drivers. An entry in the discrete I/O column of the MCU Pin Characteristics table indicates that a pin has an alternate I/O function. The port designation is given when it applies. Refer to the MCU Block Diagram for information about port organization.

Table 2 MCU Pin Characteristic

Pin Mnemonic	Output Driver	Input Synchronized	Input Hysteresis	Discrete I/O	Port Designation
ADDR23/CS10/ECLK	A	Y	N	O	—
ADDR[22:19]/CS[9:6]	A	Y	N	O	PC[6:3]
ADDR[18:0]	A	Y	N	—	—
\overline{AS}	B	Y	N	I/O	PE5
\overline{AVEC}	B	Y	N	I/O	PE2
\overline{BERR}	B	Y	N	—	—
$\overline{BG/CS1}$	B	—	—	—	—
$\overline{BGACK/CS2}$	B	Y	N	—	—
$\overline{BKPT/DSCLK}$	—	Y	Y	—	—
$\overline{BR/CS0}$	B	Y	N	—	—
CLKOUT	A	—	—	—	—
\overline{CSBOOT}	B	—	—	—	—
DATA[15:0] ¹	Aw	Y	N	—	—
\overline{DS}	B	Y	N	I/O	PE4
$\overline{DSACK1}$	B	Y	N	I/O	PE1
$\overline{DSACK0}$	B	Y	N	I/O	PE0
DSI/IFETCH	A	Y	Y	—	—
DSO/IPIPE	A	—	—	—	—
EXTAL ²	—	—	Special	—	—
FC[2:0]/CS[5:3]	A	Y	N	O	PC[2:0]
FREEZE/QUOT	A	—	—	—	—
\overline{HALT}	Bo	Y	N	—	—
$\overline{IRQ[7:1]}$	B	Y	Y	I/O	PF[7:1]
MISO	Bo	Y	Y	I/O	PQS0
MODCLK ¹	B	Y	N	I/O	PF0
MOSI	Bo	Y	Y	I/O	PQS1
PCS0/ \overline{SS}	Bo	Y	Y	I/O	PQS3
PCS[3:1]	Bo	Y	Y	I/O	PQS[6:4]
R/W	A	Y	N	—	—
\overline{RESET}	Bo	Y	Y	—	—
\overline{RMC}	B	Y	N	I/O	PE3
RXD	—	N	N	—	—
SCK	Bo	Y	Y	I/O	PQS2
SIZ[1:0]	B	Y	N	I/O	PE[7:6]

Table 7 SIM Address Map (Continued)

Access	Address	15	8 7	0
S	\$YFFA56	CHIP-SELECT OPTION 2 (CSOR2)		
S	\$YFFA58	CHIP-SELECT BASE 3 (CSBAR3)		
S	\$YFFA5A	CHIP-SELECT OPTION 3 (CSOR3)		
S	\$YFFA5C	CHIP-SELECT BASE 4 (CSBAR4)		
S	\$YFFA5E	CHIP-SELECT OPTION 4 (CSOR4)		
S	\$YFFA60	CHIP-SELECT BASE 5 (CSBAR5)		
S	\$YFFA62	CHIP-SELECT OPTION 5 (CSOR5)		
S	\$YFFA64	CHIP-SELECT BASE 6 (CSBAR6)		
S	\$YFFA66	CHIP-SELECT OPTION 6 (CSOR6)		
S	\$YFFA68	CHIP-SELECT BASE 7 (CSBAR7)		
S	\$YFFA6A	CHIP-SELECT OPTION 7 (CSOR7)		
S	\$YFFA6C	CHIP-SELECT BASE 8 (CSBAR8)		
S	\$YFFA6E	CHIP-SELECT OPTION 8 (CSOR8)		
S	\$YFFA70	CHIP-SELECT BASE 9 (CSBAR9)		
S	\$YFFA72	CHIP-SELECT OPTION 9 (CSOR9)		
S	\$YFFA74	CHIP-SELECT BASE 10 (CSBAR10)		
S	\$YFFA76	CHIP-SELECT OPTION 10 (CSOR10)		
	\$YFFA78	NOT USED		NOT USED
	\$YFFA7A	NOT USED		NOT USED
	\$YFFA7C	NOT USED		NOT USED
	\$YFFA7E	NOT USED		NOT USED

Y = M111, where M is the logic state of the module mapping (MM) bit in the SIMCR.

3.2 System Configuration and Protection

This functional block provides configuration control for the entire MCU. It also performs interrupt arbitration, bus monitoring, and system test functions. MCU system protection includes a bus monitor, a HALT monitor, a spurious interrupt monitor, and a software watchdog timer. These functions have been made integral to the microcontroller to reduce the number of external components in a complete control system.

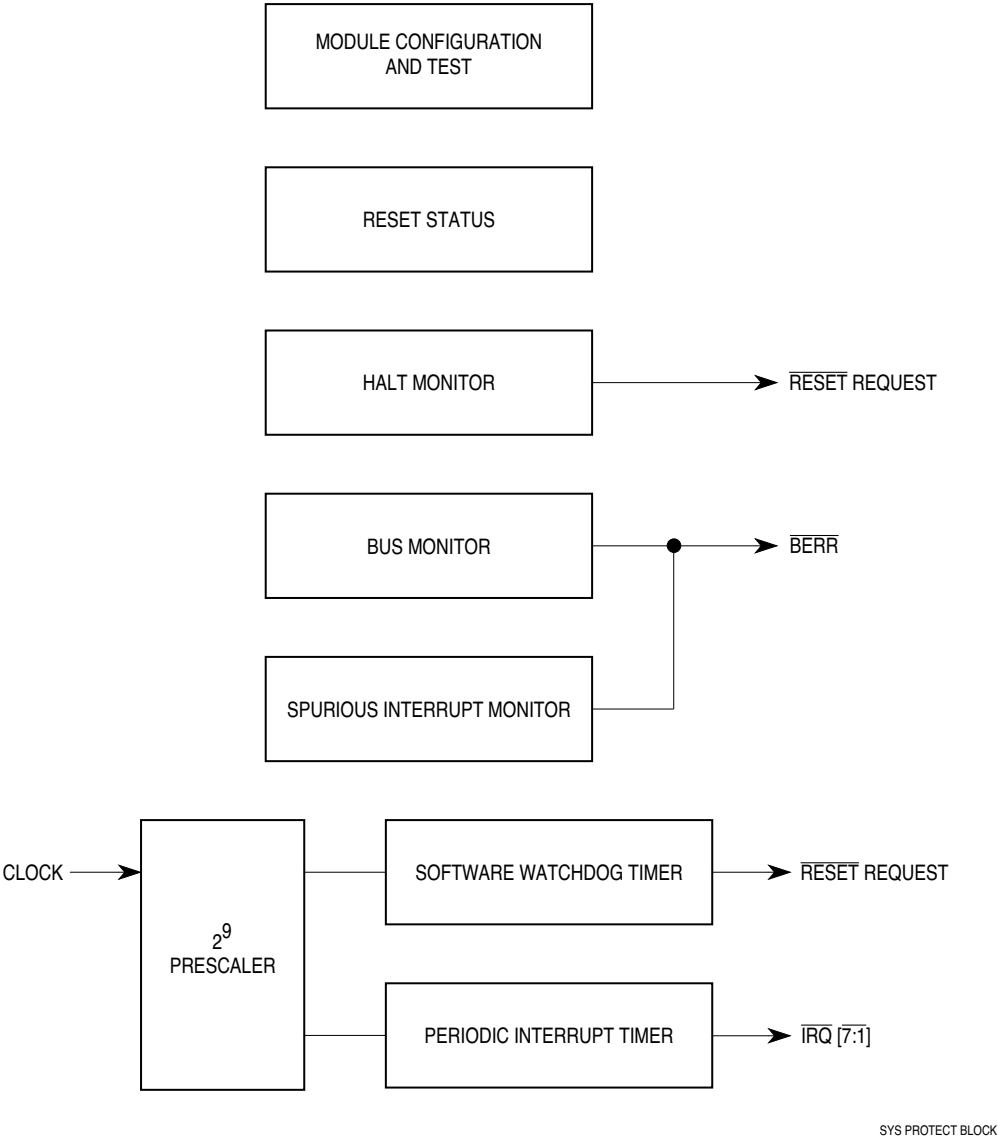


Figure 6 System Configuration and Protection Block

3.2.1 System Configuration

The SIM controls MCU configuration during normal operation and during internal testing.

SIMCR —SIM Configuration Register													\$YFFA00		
15	14	13	12	11	10	9	8	7	6	5	4	3	0		
EXOFF	FRZSW	FRZBM	0	SLVEN	0	SHEN		SUPV	MM	0	0	IARB			
RESET:															
0	0	0	0	DATA11	0	0	0	1	1	0	0	1	1	1	1

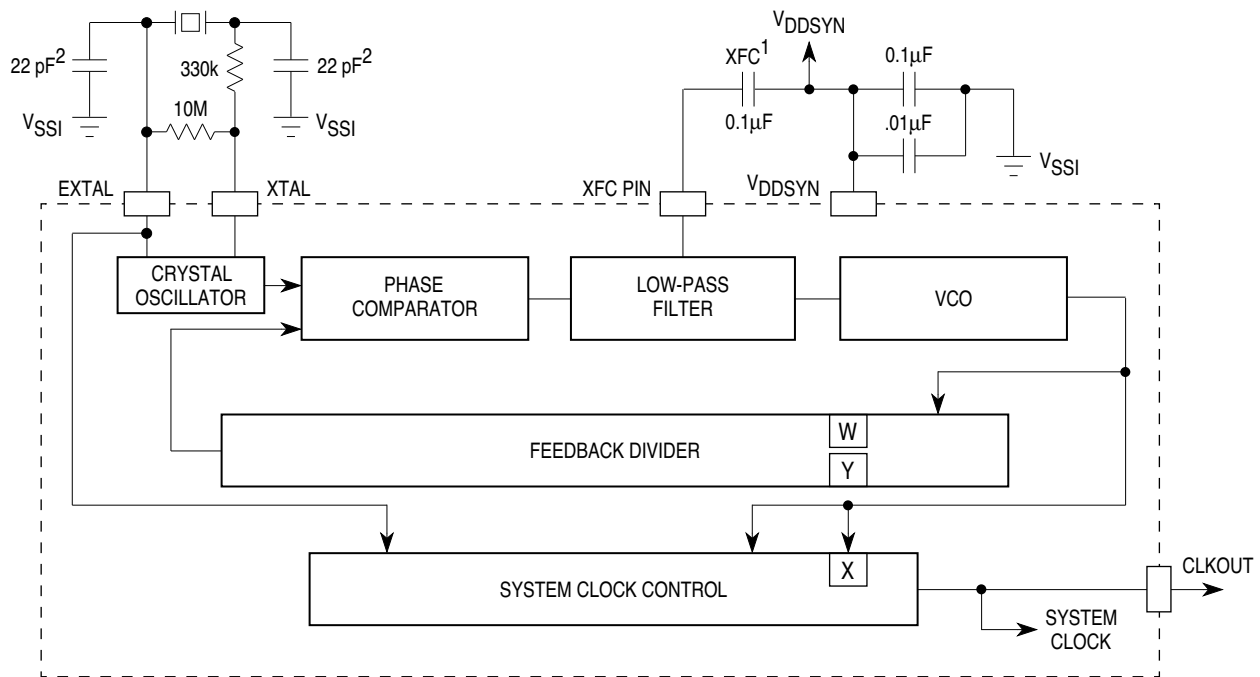
The SIM configuration register controls system configuration. It can be read or written at any time, except for the module mapping (MM) bit, which can be written only once.

3.3 System Clock

The system clock in the SIM provides timing signals for the IMB modules and for an external peripheral bus. Because MCU operation is fully static, register and memory contents are not affected when the clock rate changes. System hardware and software support changes in the clock rate during operation.

The system clock signal can be generated in three ways. An internal phase-locked loop can synthesize the clock from an internal or external frequency source, or the clock signal can be input from an external source.

Following is a block diagram of the clock submodule.



1. MUST BE LOW-LEAKAGE CAPACITOR (INSULATION RESISTANCE 30,000 MΩ OR GREATER).
2. RESISTANCE AND CAPACITANCE BASED ON A TEST CIRCUIT CONSTRUCTED WITH A DAISHINKU DMX-38 32.768-kHz CRYSTAL. SPECIFIC COMPONENTS MUST BE BASED ON CRYSTAL TYPE. CONTACT CRYSTAL VENDOR FOR EXACT CIRCUIT.

SYS CLOCK
BLOCK 32KHZ

Figure 7 System Clock Block Diagram

3.3.1 Clock Sources

The state of the clock mode (MODCLK) pin during reset determines the clock source. When MODCLK is held high during reset, the clock synthesizer generates a clock signal from either a crystal oscillator or an external reference input. Clock synthesizer control register SYNCR determines operating frequency and various modes of operation. When MODCLK is held low during reset, the clock synthesizer is disabled, and an external system clock signal must be applied. When the synthesizer is disabled, SYNCR control bits have no effect.

A reference crystal must be connected between the EXTAL and XTAL pins to use the internal oscillator. Use of a 32.768-kHz crystal is recommended. These crystals are inexpensive and readily available. If an external reference signal or an external system clock signal is applied through the EXTAL pin, the XTAL pin must be left floating. External reference signal frequency must be less than or equal to maximum specified reference frequency. External system clock signal frequency must be less than or equal to maximum specified system clock frequency.

When an external system clock signal is applied (i.e., the PLL is not used), duty cycle of the input is critical, especially at near maximum operating frequencies. The relationship between clock signal duty cycle and clock signal period is expressed:

$$\text{Minimum external clock period} = \frac{\text{minimum external clock high/low time}}{50\% - \text{percentage variation of external clock input duty cycle}}$$

3.3.2 Clock Synthesizer Operation

A voltage controlled oscillator (VCO) generates the system clock signal. A portion of the clock signal is fed back to a divider/counter. The divider controls the frequency of one input to a phase comparator. The other phase comparator input is a reference signal, either from the internal oscillator or from an external source. The comparator generates a control signal proportional to the difference in phase between its two inputs. The signal is low-pass filtered and used to correct VCO output frequency.

The synthesizer locks when VCO frequency is identical to reference frequency. Lock time is affected by the filter time constant and by the amount of difference between the two comparator inputs. Whenever comparator input changes, the synthesizer must re-lock. Lock status is shown by the SLOCK bit in SYNCR.

The MCU does not come out of reset state until the synthesizer locks. Crystal type, characteristic frequency, and layout of external oscillator circuitry affect lock time.

The low-pass filter requires an external low-leakage capacitor, typically 0.1 μF , connected between the XFC and V_{DDSYN} pins.

V_{DDSYN} is used to power the clock circuits. A separate power source increases MCU noise immunity and can be used to run the clock when the MCU is powered down. Use a quiet power supply as the V_{DDSYN} source, since PLL stability depends on the VCO, which uses this supply. Place adequate external bypass capacitors as close as possible to the V_{DDSYN} pin to ensure stable operating frequency.

When the clock synthesizer is used, control register SYNCR determines operating frequency and various modes of operation. SYNCR can be read only when the processor is operating at the supervisor privilege level.

The SYNCR X bit controls a divide by two prescaler that is not in the synthesizer feedback loop. Setting X doubles clock speed without changing VCO speed. There is no VCO relock delay. The SYNCR W bit controls a 3-bit prescaler in the feedback divider. Setting W increases VCO speed by a factor of four. The SYNCR Y field determines the count modulus for a modulo 64 down counter, causing it to divide by a value of $Y + 1$. When either W or Y value changes, there is a VCO relock delay.

Clock frequency is determined by SYNCR bit settings as follows:

$$F_{\text{SYSTEM}} = F_{\text{REFERENCE}} [4(Y + 1)(2^{2W} + X)]$$

In order for the device to perform correctly, the clock frequency selected by the W, X, and Y bits must be within the limits specified for the MCU.

The VCO frequency is twice the system clock frequency if $X = 1$ or four times the system clock frequency if $X = 0$.

The reset state of SYNCR (\$3F00) produces a modulus-64 count.

CSORBT —Chip-Select Option Register Boot ROM

\$YFFA4A

15	14	13	12	11	10	9	6	5	4	3	1	0
MODE	BYTE	R/W	STRB	DSACK	SPACE	IPL	AVEC					
RESET:												
0	1	1	1	1	0	1	1	0	1	1	0	0

CSOR[10:0] —Chip-Select Option Registers

\$YFFA4E–\$YFFA76

15	14	13	12	11	10	9	6	5	4	3	1	0
MODE	BYTE	R/W	STRB	DSACK	SPACE	IPL	AVEC					
RESET:												
0	0	0	0	0	0	0	0	0	0	0	0	0

CSORBT, the option register for \overline{CSBOOT} , contains special reset values that support bootstrap operations from peripheral memory devices.

The following bit descriptions apply to both CSORBT and CSOR[10:0] option registers.

MODE — Asynchronous/Synchronous Mode

0 = Asynchronous mode selected (chip-select assertion determined by internal or external bus control signals)

1 = Synchronous mode selected (chip-select assertion synchronized with ECLK signal)

In asynchronous mode, the chip select is asserted synchronized with \overline{AS} or \overline{DS} .

The \overline{DSACK} field is not used in synchronous mode because a bus cycle is only performed as a synchronous operation. When a match condition occurs on a chip select programmed for synchronous operation, the chip select signals the EBI that an ECLK cycle is pending.

BYTE — Upper/Lower Byte Option

This field is used only when the chip-select 16-bit port option is selected in the pin assignment register. The following table lists upper/lower byte options.

Byte	Description
00	Disable
01	Lower Byte
10	Upper Byte
11	Both Bytes

R/W — Read/Write

This field causes a chip select to be asserted only for a read, only for a write, or for both read and write. Refer to the following table for options available.

R/W	Description
00	Reserved
01	Read Only
10	Write Only
11	Read/Write

STRB — Address Strobe/Data Strobe

0 = Address strobe

1 = Data strobe

This bit controls the timing for assertion of a chip select in asynchronous mode. Selecting address strobe causes chip select to be asserted synchronized with address strobe. Selecting data strobe causes chip select to be asserted synchronized with data strobe.

DSACK — Data and Size Acknowledge

This field specifies the source of $\overline{\text{DSACK}}$ in asynchronous mode. It also allows the user to adjust bus timing with internal $\overline{\text{DSACK}}$ generation by controlling the number of wait states that are inserted to optimize bus speed in a particular application. The following table shows the $\overline{\text{DSACK}}$ field encoding. The fast termination encoding (1110) is used for two-cycle access to external memory.

DSACK	Description
0000	No Wait States
0001	1 Wait State
0010	2 Wait States
0011	3 Wait States
0100	4 Wait States
0101	5 Wait States
0110	6 Wait States
0111	7 Wait States
1000	8 Wait States
1001	9 Wait States
1010	10 Wait States
1011	11 Wait States
1100	12 Wait States
1101	13 Wait States
1110	Fast Termination
1111	External $\overline{\text{DSACK}}$

SPACE — Address Space

Use this option field to select an address space for the chip-select logic. The CPU32 normally operates in supervisor or user space, but interrupt acknowledge cycles must take place in CPU space.

Space Field	Address Space
00	CPU Space
01	User Space
10	Supervisor Space
11	Supervisor/User Space

IPL — Interrupt Priority Level

If the space field is set for CPU space (00), chip-select logic can be used for interrupt acknowledge. During an interrupt acknowledge cycle, the priority level on address lines ADDR[3:1] is compared to the value in the IPL field. If the values are the same, a chip select is asserted, provided that other option register conditions are met. The following table shows IPL field encoding.

IPL	Description
000	Any Level
001	IPL1
010	IPL2
011	IPL3
100	IPL4
101	IPL5
110	IPL6
111	IPL7

This field only affects the response of chip selects and does not affect interrupt recognition by the CPU. Any level means that chip select is asserted regardless of the level of the interrupt acknowledge cycle.

5.1.2 Input Capture/Input Transition Counter (ITC)

Any channel of the TPU can capture the value of a specified TCR upon the occurrence of each transition or specified number of transitions, and then generate an interrupt request to notify the CPU. A channel can perform input captures continually, or a channel can detect a single transition or specified number of transitions, then cease channel activity until reinitialization. After each transition or specified number of transitions, the channel can generate a link to a sequential block of up to eight channels. The user specifies a starting channel of the block and the number of channels within the block. The generation of links depends on the mode of operation. In addition, after each transition or specified number of transitions, one byte of the parameter RAM (at an address specified by channel parameter) can be incremented and used as a flag to notify another channel of a transition.

5.1.3 Output Compare (OC)

The output compare function generates a rising edge, falling edge, or a toggle of the previous edge in one of three ways:

1. Immediately upon CPU initiation, thereby generating a pulse with a length equal to a programmable delay time.
2. At a programmable delay time from a user-specified time.
3. Continuously. Upon receiving a link from a channel, OC references, without CPU interaction, a specifiable period and calculates an offset:

$$\text{Offset} = \text{Period} * \text{Ratio}$$

where Ratio is a parameter supplied by the user.

This algorithm generates a 50% duty-cycle continuous square wave with each high/low time equal to the calculated OFFSET. Due to offset calculation, there is an initial link time before continuous pulse generation begins.

5.1.4 Pulse-Width Modulation (PWM)

The TPU can generate a pulse-width modulation waveform with any duty cycle from zero to 100% (within the resolution and latency capability of the TPU). To define the PWM, the CPU provides one parameter that indicates the period and another parameter that indicates the high time. Updates to one or both of these parameters can direct the waveform change to take effect immediately, or coherently beginning at the next low-to-high transition of the pin.

5.1.5 Synchronized Pulse-Width Modulation (SPWM)

The TPU generates a PWM waveform in which the CPU can change the period and/or high time at any time. When synchronized to a time function on a second channel, the synchronized PWM low-to-high transitions have a time relationship to transitions on the second channel.

5.1.6 Period Measurement with Additional Transition Detect (PMA)

This function and the following function are used primarily in toothed-wheel speed-sensing applications, such as monitoring rotational speed of an engine. The period measurement with additional transition detect function allows for a special-purpose 23-bit period measurement. It can detect the occurrence of an additional transition (caused by an extra tooth on the sensed wheel) indicated by a period measurement that is less than a programmable ratio of the previous period measurement.

Once detected, this condition can be counted and compared to a programmable number of additional transitions detected before TCR2 is reset to \$FFFF. Alternatively, a byte at an address specified by a channel parameter can be read and used as a flag. A nonzero value of the flag indicates that TCR2 is to be reset to \$FFFF once the next additional transition is detected.

5.2.9 Frequency Measurement (FQM)

FQM counts the number of input pulses to a TPU channel during a user-defined window period. The function has single shot and continuous modes. No pulses are lost between sample windows in continuous mode. The user selects whether to detect pulses on the rising or falling edge. This function is intended for high speed measurement; measurement of slow pulses with noise rejection can be made with PTA.

5.2.10 Hall Effect Decode (HALLD)

This function decodes the sensor signals from a brushless motor, along with a direction input from the CPU, into a state number. The function supports two- or three-sensor decoding. The decoded state number is written into a COMM channel, which outputs the required commutation drive signals. In addition to brushless motor applications, the function can have more general applications, such as decoding “option” switches.

5.3 Programmer's Model

The TPU control register address map occupies 512 bytes. The “Access” column in the TPU address map below indicates which registers are accessible only at the supervisor privilege level and which can be assigned to either the supervisor or user privilege level, according to the value of the SUPV bit in the TPUMCR.

Table 22 TPU Address Map

Access	Address	15	8	7	0
S	\$YFFE00	TPU MODULE CONFIGURATION REGISTER (TPUMCR)			
S	\$YFFE02	TEST CONFIGURATION REGISTER (TCR)			
S	\$YFFE04	DEVELOPMENT SUPPORT CONTROL REGISTER (DSCR)			
S	\$YFFE06	DEVELOPMENT SUPPORT STATUS REGISTER (DSSR)			
S	\$YFFE08	TPU INTERRUPT CONFIGURATION REGISTER (TICR)			
S	\$YFFE0A	CHANNEL INTERRUPT ENABLE REGISTER (CIER)			
S	\$YFFE0C	CHANNEL FUNCTION SELECTION REGISTER 0 (CFSR0)			
S	\$YFFE0E	CHANNEL FUNCTION SELECTION REGISTER 1 (CFSR1)			
S	\$YFFE10	CHANNEL FUNCTION SELECTION REGISTER 2 (CFSR2)			
S	\$YFFE12	CHANNEL FUNCTION SELECTION REGISTER 3 (CFSR3)			
S/U	\$YFFE14	HOST SEQUENCE REGISTER 0 (HSQR0)			
S/U	\$YFFE16	HOST SEQUENCE REGISTER 1 (HSQR1)			
S/U	\$YFFE18	HOST SERVICE REQUEST REGISTER 0 (HSRR0)			
S/U	\$YFFE1A	HOST SERVICE REQUEST REGISTER 1 (HSRR1)			
S	\$YFFE1C	CHANNEL PRIORITY REGISTER 0 (CPR0)			
S	\$YFFE1E	CHANNEL PRIORITY REGISTER 1 (CPR1)			
S	\$YFFE20	CHANNEL INTERRUPT STATUS REGISTER (CISR)			
S	\$YFFE22	LINK REGISTER (LR)			
S	\$YFFE24	SERVICE GRANT LATCH REGISTER (SGLR)			
S	\$YFFE26	DECODED CHANNEL NUMBER REGISTER (DCNR)			

Y = M111, where M represents the logic state of the module mapping (MM) bit in the SIMCR.

5.4 Parameter RAM

Parameter RAM occupies 256 bytes at the top of the TPU module address map. Channel parameters are organized as 128 16-bit words. However, only 100 words are actually implemented. The parameter RAM address map shows how parameter words are organized in memory.

Table 23 TPU Parameter RAM Address Map

Channel Number	Base Address	Parameter Address							
		0	1	2	3	4	5	6	7
0	\$YFFFF##	00	02	04	06	08	0A	—	—
1	\$YFFFF##	10	12	14	16	18	1A	—	—
2	\$YFFFF##	20	22	24	26	28	2A	—	—
3	\$YFFFF##	30	32	34	36	38	3A	—	—
4	\$YFFFF##	40	42	44	46	48	4A	—	—
5	\$YFFFF##	50	52	54	56	58	5A	—	—
6	\$YFFFF##	60	62	64	66	68	6A	—	—
7	\$YFFFF##	70	72	74	76	78	7A	—	—
8	\$YFFFF##	80	82	84	86	88	8A	—	—
9	\$YFFFF##	90	92	94	96	98	9A	—	—
10	\$YFFFF##	A0	A2	A4	A6	A8	AA	—	—
11	\$YFFFF##	B0	B2	B4	B6	B8	BA	—	—
12	\$YFFFF##	C0	C2	C4	C6	C8	CA	—	—
13	\$YFFFF##	D0	D2	D4	D6	D8	DA	—	—
14	\$YFFFF##	E0	E2	E4	E6	E8	EA	EC	EE
15	\$YFFFF##	F0	F2	F4	F6	F8	FA	FC	FE

—= Not Implemented

Y = M111, where M represents the logic state of the MM bit in the SIMCR.

5.5 TPU Registers

The TPU memory map contains three groups of registers:

- System Configuration Registers
- Channel Control and Status Registers
- Development Support and Test Verification Registers

5.5.1 System Configuration Registers

TPUMCR — TPU Module Configuration Register

\$YFFE00

15	14	13	12	11	10	9	8	7	6	5	4	3	0
STOP	TCR1P	TCR2P	EMU	T2CG	STF	SUPV	PSCK	0	0			IARB	

RESET:

0 0 0 0 0 0 0 0 1 0 0 0 0 0

STOP — Stop Bit

- 0 = TPU operating normally
- 1 = Internal clocks shut down

CHX[1:0]	Service	Guaranteed Time Slots
00	Disabled	—
01	Low	4 out of 7
10	Middle	2 out of 7
11	High	1 out of 7

5.5.3 Development Support and Test Registers

These registers are used for custom microcode development or for factory test. Describing the use of the registers is beyond the scope of this technical summary. Register names and addresses are given for reference only. Please refer to the *TPU Reference Manual* (TPURM/AD) for more information.

DSCR — Development Support Control Register	\$YFFE04
DSSR — Development Support Status Register	\$YFFE06
LR — Link Register	\$YFFE22
SGLR — Service Grant Latch Register	\$YFFE24
DCNR — Decoded Channel Number Register	\$YFFE26
TCR — Test Configuration Register	\$YFFE02

The TCR is used for factory test of the MCU.

The system software must stop each submodule before asserting STOP to avoid complications at re-start and to avoid data corruption. The SCI submodule receiver and transmitter should be disabled, and the operation should be verified for completion before asserting STOP. The QSPI submodule should be stopped by asserting the HALT bit in SPCR3 and by asserting STOP after the HALTA flag is set.

FRZ1 — Freeze 1

- 0 = Ignore the FREEZE signal on the IMB
- 1 = Halt the QSPI (on a transfer boundary)

FRZ1 determines what action is taken by the QSPI when the FREEZE signal of the IMB is asserted. FREEZE is asserted whenever the CPU enters the background mode.

FRZ0 — Freeze 0

Reserved

Bits [12:8] — Not Implemented

SUPV — Supervisor/Unrestricted

- 0 = User access
- 1 = Supervisor access

SUPV defines the assignable QSM registers as either supervisor-only data space or unrestricted data space.

IARB — Interrupt Arbitration Identification Number

The IARB field is used to arbitrate between simultaneous interrupt requests of the same priority. Each module that can generate interrupt requests must be assigned a unique, non-zero IARB field value. Refer to **3.8 Interrupts** for more information.

QTEST — QSM Test Register

\$YFFC02

QTEST is used during factory testing of the QSM. Accesses to QTEST must be made while the MCU is in test mode.

QILR — QSM Interrupt Levels Register

\$YFFC04

15	14	13	11	10	8	7	0
0	0	ILQSPI			ILSCI		QIVR

RESET:

0 0 0 0 0 0 0 0

QILR determines the priority level of interrupts requested by the QSM and the vector used when an interrupt is acknowledged.

ILQSPI — Interrupt Level for QSPI

ILQSPI determines the priority of QSPI interrupts. This field must be given a value between \$0 (interrupts disabled) to \$7 (highest priority).

ILSCI — Interrupt Level of SCI

ILSCI determines the priority of SCI interrupts. This field must be given a value between \$0 (interrupts disabled) to \$7 (highest priority).

If ILQSPI and ILSCI are the same nonzero value, and both submodules simultaneously request interrupt service, QSPI has priority.

Table 26 Effect of DDRQS on QSM Pin Function

QSM Pin	Mode	DDRQS Bit	Bit State	Pin Function
MISO	Master	DDQ0	0	Serial Data Input to QSPI
			1	Disables Data Input
	Slave		0	Disables Data Output
			1	Serial Data Output from QSPI
MOSI	Master	DDQ1	0	Disables Data Output
			1	Serial Data Output from QSPI
	Slave		0	Serial Data Input to QSPI
			1	Disables Data Input
SCK ¹	Master	DDQ2	0	Disables Clock Output
			1	Clock Output from QSPI
	Slave		0	Clock Input to QSPI
			1	Disables Clock Input
PCS0/ \overline{SS}	Master	DDQ3	0	Assertion Causes Mode Fault
			1	Chip-Select Output
	Slave		0	QSPI Slave Select Input
			1	Disables Select Input
PCS[3:1]	Master	DDQ[4:6]	0	Disables Chip-Select Output
			1	Chip-Select Output
	Slave		0	Inactive
			1	Inactive
TXD ²	Transmit	DDQ7	X	Serial Data Output from SCI
RXD	Receive	None	NA	Serial Data Input to SCI

NOTES:

1. PQS2 is a digital I/O pin unless the SPI is enabled (SPE in SPCR1 set), in which case it becomes SPI serial clock SCK.
2. PQS7 is a digital I/O pin unless the SCI transmitter is enabled (TE in SCCR1 = 1), in which case it becomes SCI serial output TXD.

DDRQS determines the direction of the TXD pin only when the SCI transmitter is disabled. When the SCI transmitter is enabled, the TXD pin is an output.

Command RAM is used by the QSPI when in master mode. The CPU writes one byte of control information to this segment for each QSPI command to be executed. The QSPI cannot modify information in command RAM.

Command RAM consists of 16 bytes. Each byte is divided into two fields. The peripheral chip-select field enables peripherals for transfer. The command control field provides transfer options.

A maximum of 16 commands can be in the queue. Queue execution by the QSPI proceeds from the address in NEWQP through the address in ENDQP. (Both of these fields are in SPCR2.)

CONT — Continue

- 0 = Control of chip selects returned to PORTQS after transfer is complete.
- 1 = Peripheral chip selects remain asserted after transfer is complete.

BITSE — Bits per Transfer Enable

- 0 = 8 bits
- 1 = Number of bits set in BITS field of SPCR0

DT — Delay after Transfer

The QSPI provides a variable delay at the end of serial transfer to facilitate the interface with peripherals that have a latency requirement. The delay between transfers is determined by the SPCR1 DTL field.

DSCK — PCS to SCK Delay

- 0 = PCS valid to SCK transition is one-half SCK.
- 1 = SPCR1 DSCKL field specifies delay from PCS valid to SCK.

PCS[3:0] — Peripheral Chip Select

Use peripheral chip-select bits to select an external device for serial data transfer. More than one peripheral chip select can be activated at a time, and more than one peripheral chip can be connected to each PCS pin, provided that proper fanout is observed.

\overline{SS} — Slave Mode Select

Initiates slave mode serial transfer. If \overline{SS} is taken low when the QSPI is in master mode, a mode fault will be generated.

6.5.4 Operating Modes

The QSPI operates in either master or slave mode. Master mode is used when the MCU originates data transfers. Slave mode is used when an external device initiates serial transfers to the MCU through the QSPI. Switching between the modes is controlled by MSTR in SPCR0. Before entering either mode, appropriate QSM and QSPI registers must be properly initialized.

In master mode, the QSPI executes a queue of commands defined by control bits in each command RAM queue entry. Chip-select pins are activated, data is transmitted from transmit RAM and received into receive RAM.

In slave mode, operation proceeds in response to \overline{SS} pin activation by an external bus master. Operation is similar to master mode, but no peripheral chip selects are generated, and the number of bits transferred is controlled in a different manner. When the QSPI is selected, it automatically executes the next queue transfer to exchange data with the external device correctly.

Although the QSPI inherently supports multimaster operation, no special arbitration mechanism is provided. A mode fault flag (MODF) indicates a request for SPI master arbitration. System software must provide arbitration. Note that unlike previous SPI systems, MSTR is not cleared by a mode fault being set, nor are the QSPI pin output drivers disabled. The QSPI and associated output drivers must be disabled by clearing SPE in SPCR1.

Writing a value of zero to SCBR disables the baud rate generator.

The following table lists the SCBR settings for standard and maximum baud rates using 16.78-MHz and 20.97-MHz system clocks.

Table 27 SCI Baud Rates

Nominal Baud Rate	Actual Rate with 16.78-MHz Clock	SCBR Value	Actual Rate with 20.97-MHz Clock	SCBR Value
64*	64.0	\$1FFF	—	—
110	110.0	\$129E	110.0	\$1745
300	299.9	\$06D4	300.1	\$0888
600	599.9	\$036A	600.1	\$0444
1200	1199.7	\$0165	1200.3	\$0222
2400	2405.0	\$00DA	2400.6	\$0111
4800	4810.0	\$006D	4783.6	\$0089
9600	9532.5	\$0037	9637.6	\$0044
19200	19418.1	\$0016	19275.3	\$0022
38400	37449.1	\$000E	38550.6	\$0011
76800	74898.3	\$0007	72817.8	\$0009
Maximum Rate	524288.0	\$0001	655360.0	\$0001

SCCR1 — SCI Control Register 1

\$YFFC0A

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	LOOPS	WOMS	ILT	PT	PE	M	WAKE	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK

RESET:

0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0

SCCR1 contains SCI configuration parameters. The CPU can read and write this register at any time. The SCI can modify RWU in some circumstances. In general, interrupts enabled by these control bits are cleared by reading SCSR, then reading (receiver status bits) or writing (transmitter status bits) SCDR.

Bit 15 — Not Implemented

LOOPS — Loop Mode

- 0 = Normal SCI operation, no looping, feedback path disabled
- 1 = Test SCI operation, looping, feedback path enabled

LOOPS controls a feedback path on the data serial shifter. When loop mode is enabled, SCI transmitter output is fed back into the receive serial shifter. TXD is asserted (idle line). Both transmitter and receiver must be enabled before entering loop mode.

WOMS — Wired-OR Mode for SCI Pins

- 0 = If configured as an output, TXD is a normal CMOS output.
- 1 = If configured as an output, TXD is an open-drain output.

WOMS determines whether the TXD pin is an open-drain output or a normal CMOS output. This bit is used only when TXD is an output. If TXD is used as a general-purpose input pin, WOMS has no effect.

ILT — Idle-Line Detect Type

- 0 = Short idle-line detect (start count on first one)
- 1 = Long idle-line detect (start count on first one after stop bit(s))

PT — Parity Type

- 0 = Even parity
- 1 = Odd parity

When parity is enabled, PT determines whether parity is even or odd for both the receiver and the transmitter.

7 Standby RAM with TPU Emulation RAM

The TPURAM module contains a 2-Kbyte array of fast (two bus cycle) static RAM, which is especially useful for system stacks and variable storage. Alternately, it can be used by the TPU as emulation RAM for new timer algorithms.

7.1 Overview

The TPURAM can be mapped to any 4-Kbyte boundary in the address map, but must not overlap the module control registers. (Overlap makes the registers inaccessible.) Data can be read or written in bytes, word, or long words. TPURAM responds to both program and data space accesses. Data can be read or written in bytes, words, or long words. The TPURAM is powered by V_{DD} in normal operation. During power-down, the TPURAM contents are maintained by power on standby voltage pin V_{STBY} . Power switching between sources is automatic.

Access to the TPURAM array is controlled by the RASP field in TRAMMCR. This field can be encoded so that TPURAM responds to both program and data space accesses. This allows code to be executed from TPURAM, and permits the use of program counter relative addressing mode for operand fetches from the array.

An address map of the TPURAM control registers follows. All TPURAM control registers are located in supervisor data space.

Table 28 TPURAM Control Register Address Map

Access	Address	15	8	7	0
S	\$YFFB00	TPURAM MODULE CONFIGURATION REGISTER (TRAMMCR)			
S	\$YFFB02	TPURAM TEST REGISTER (TRAMTST)			
S	\$YFFB04	TPURAM BASE ADDRESS REGISTER (TRAMBAR)			
	\$YFFB06– \$YFFB3F	NOT USED			

Y = M111, where M is the logic state of the MM bit in the SIMCR.

7.2 TPURAM Register Block

There are three TPURAM control registers: the RAM module configuration register (TRAMMCR), the RAM test register (TRAMTST), and the RAM array base address registers (TRAMBAR).

There is an 8-byte minimum register block size for the module. Unimplemented register addresses are read as zeros, and writes have no effect.

7.3 TPURAM Registers

TRAMMCR —TPURAM Module Configuration Register

\$YFFB00

15	14	13	12	11	10	9	8	7	0
STOP	0	0	0	0	0	0	RASP	NOT USED	

RESET:

0 0 0 0 0 0 0 1

TSTOP —Stop Control

0 = RAM array operates normally.

1 = RAM array enters low-power stop mode.

This bit controls whether the RAM array is in stop mode or normal operation. Reset state is zero, for normal operation. In stop mode, the array retains its contents, but cannot be read or written by the CPU.

RASP — RAM Array Space Field

0 = TPURAM array is placed in unrestricted space

1 = TPURAM array is placed in supervisor space

TRAMTST — TPURAM Test Register

\$YFFB02

TRAMTST is used for factory testing of the TPURAM module.

TRAMBAR — TPURAM Base Address and Status Register

\$YFFB04

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ADDR 23	ADDR 22	ADDR 21	ADDR 20	ADDR 19	ADDR 18	ADDR 17	ADDR 16	ADDR 15	ADDR 14	ADDR 13	ADDR 12	ADDR 11	NOT USED		RAMDS
RESET:															
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

ADDR[23:11] — RAM Array Base Address

These bits specify address lines ADDR[23:11] of the base address of the RAM array when enabled.

RAMDS — RAM Array Disable

0 = RAM array is enabled

1 = RAM array is disabled

The RAM array is disabled by internal logic after a master reset. Writing a valid base address to the RAM array base address field (bits [15:3]) automatically clears RAMDS, enabling the RAM array.

7.4 TPURAM Operation

There are six TPURAM operating modes, as follows:

1. The TPURAM module is in normal mode when powered by V_{DD} . The array can be accessed by byte, word, or long word. A byte or aligned word (high-order byte is at an even address) access only takes one bus cycle or two system clocks. A long word or misaligned word access requires two bus cycles.
2. Standby mode is intended to preserve TPURAM contents when V_{DD} is removed. TPURAM contents are maintained by V_{STBY} . Circuitry within the TPURAM module switches to the higher of V_{DD} or V_{STBY} with no loss of data. When TPURAM is powered by V_{STBY} , access to the array is not guaranteed.
3. Reset mode allows the CPU to complete the current bus cycle before resetting. When a synchronous reset occurs while a byte or word TPURAM access is in progress, the access will be completed. If reset occurs during the first word access of a long-word operation, only the first word access will be completed. If reset occurs during the second word access of a long word operation, the entire access will be completed. Data being read from or written to the RAM may be corrupted by asynchronous reset.
4. Test mode functions in conjunction with the SIM test functions. Test mode is used during factory test of the MCU.
5. Writing the STOP bit of TRAMMCR causes the TPURAM module to enter stop mode. The TPURAM array is disabled (which allows external logic to decode TPURAM addresses, if necessary), but all data is retained. If V_{DD} falls below V_{STBY} during stop mode, internal circuitry switches to V_{STBY} , as in standby mode. Stop mode is exited by clearing the STOP bit.
6. The TPURAM array may be used to emulate the microcode ROM in the TPU module. This provides a means of developing custom TPU code. The TPU selects TPU emulation mode. While in TPU emulation mode, the access timing of the TPURAM module matches the timing of the TPU microinstruction ROM to ensure accurate emulation. Normal accesses via the IMB are inhibited and the control registers have no effect, allowing external RAM to emulate the TPURAM at the same addresses.



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